FT_TAD_014_G_30

Adhesive Silicone

TAD_014_G is a highly conductive and anti-corrosion silicone 1-part adhesive by liquid addition. It hardens at a high temperature above 100°C to obtain a solid but still elastic rubber and has excellent adhesion without primer on most surfaces. The adhesive has good thermal conductivity. It can be used at temperatures up to 260°C and does not corrode copper or copper alloys when fully cured. It is characterized by high resistance to water, acids, bases and most organic solvents and is particularly suitable for applications where high thermal conductivity, adhesion, fast curing and controlled and precise application are essential

Application areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR ll Module, etc.

Technical characteristics

Features	TAD_014_G	Unit	Tolerance	Test Method
Material	Silicone			
Color	Gray			VisuAl
Denisty	2.0	g/cm3	-	ASTM D792
Hardness (Shore A)	67	Shore A	-	-
Viscosity	43	Pas		ASTM D2196
Tensile strength	3.1	Mpa	-	-
Elongation at break	70	%	-	-
Curing time	30	min	-	100°C
Thermal conductivity	1.4	W/mK	-	ASTM D5470
Volumetric thermal expansion coefficient	562	x 10^{-6}/K	-	-
Linear thermal expansion coefficient	187	x 10^{-6}/K	-	-
Temperature use	-50 + 260	°C	-	-
Breakdown voltage	22.5	kV/mm	-	ASTM D2196
Volume resistance	7.7 x 10^{15}	Ohm - cm	-	-
Surface resistivity	1.3 x 10^{15}	Ohm - cm	-	-

The results were obtained under laboratory conditions and should be considered only as an indication. As AB2E has no control over its customers' equipment and many other factors, it is the user's responsibility to carry out its own tests to ensure that the product corresponds to its needs.